JIG for Bond Strength Test

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URL http://www.olm-international.jp/olm_int
TS001: Leadframe Ball Shear

The leadframe island is gripped by the small vise.

Support Slide Plate
TS002WB: Leadframe Pull/Ball Shear

TS002W: Wire Pull

TS002B: Ball Shear

TS002WB: Pull/Shear
Other Variation of TS002 Series

- TS002WBSC: Bar Clamp
- TS002V: Vacuum Clamp
- TS002M: Twin Clamp
- TS002HV: Vertical Clamp
- TS002CAM: CAM Clamp
TS003: Wafer Chuck

- TS003-150: 100/125/150mm
- TS003-200: 100/125/150/200mm
- TS003-300: 150/200/300mm
TS004: Vacuum Clamp

TS004-80: 80mm Sq.

All Hole Size is 3mm dia.
Each Hole Has Open/ Close valve.

TS004-80CLP: Vacuum Chuck with Clamp

TS004-120: 120mm Sq.
TS005: Die Shear (Room Temperature)

- Slide Block Height Adjustment

- Heavy Duty: 4000Plus
  Up to 100kg

TS005-MR: The stopper height is adjusted by micrometer.
TS005H: Hot Die Shear

Up to 350°C
The temperature controller (#TSTP-CTL100/200) is necessary.

TS005H-4000

TS005H-Plus

TS005H-SL
Quick Release Slider
TS007: Universal Package

DIL Package, Substrate etc.
TS008: Universal

Chip Carrier, Substrate
Other Variation of TS008 Series

TS008F: Small Die/ Packages

TS008-180: 180mm Travel
TS009: Changeable Slide Block

Universal Jig with Changeable Slide Block. We will make it suitable design for your requests.
TS011: Stud Pull Test

Including: Stud Tool/ Stud cup (25mmSq.)
Options: Stud(each size)/ Support Plate (40mm Sq.)

Please ask us for “Vertical Stud Pull for 4000Plus.”
TS019: Substrate/ Package

TS019-150

TS019S: Large Package

TS019-HS
TS022: Tilt Work Holder with Vise Jig

Tilt Angle: Up to 60 degrees

Can Be Fixed Another Type Jig.
TS120: Vacuum Chuck

Location Pins, Vacuum area
TS122: Vacuum Chuck for Frame Substrate
TS140: Hot Die Shear Test for Thin Substrate
TS141: TO Package

Can be used both type TO packages.

Up to 10 Packages

Cannot use these packages.
TS143: Heat Block of Wire Bonder

This jig uses the heat block and window clamper of the wire bonder which are Shinkawa and K&S machine.

TS143VM: Vertical Movement
TS157: Strong Clamp for Leadframe

For:
LED leadframe.
The pull test strength is over 100 grams.
TS179: Heated Vise/ Vacuum Clamp
TS180: LED Leadframe

Option: Handle for Sample Plate

TS180: Room Temperature Wire Pull and Ball Shear
TS180H: Hot Die Shear
TS183: Leadframe with Heat Sink

Ceramic Heat Sink

Leadframe Heat Sink
TS184: Zone Shear

Keep leveling during shear test.
TS185: Changeable Large Slide Block
TS190: Flat Surface Wafer Chuck

Changeable Vacuum Area: 125/150/200mm dia.
TS194: Chip-On-Wafer Shear Test

This Jig is for 100mm Wafer.
TS200: Heavy Duty Vise

Changeable Vise Block
TS202: 3 or 4 Point Bending

3 Point Tool

4 Point Tool
TS203: SEMI Based Chip Bending

SEMI G86-0303 Test Method
TS211: ASE-Q200 Based Bending
TS216: Vertical Lead Frame Hot Test
TS217: Syringe Push Force test
TS221: Cantilever Chip Bending

SEMI G96-1014 Test Method
TS223: Dual Square Vise

No need re-Chacking the samples
The sample is always holding any directions.
Work Holders

WB-Worm: Worm Gear Rotation

WH5000: Adjust Height Workholder for 5000

WB400P: Heavy Duty Workholder for 4000Plus

OLM-WH: Adjust Height
Accessories

Sample Grip for X-Ray CT System

Mechanical Grip for Strong Tweezer Pull Test